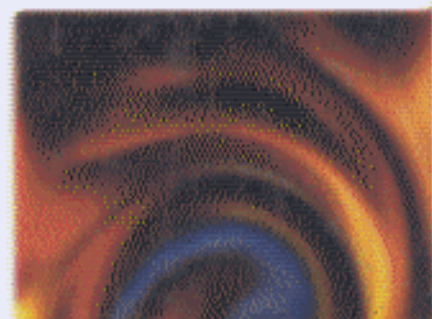


EP&P
ELECTRONIC PACKAGING & PRODUCTION



ELECTRONIC PACKAGING AND INTERCONNECTION HANDBOOK

Suranaree University of Technology



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